TOSHIBA Transistor Silicon NPN Epitaxial Planar Type

# MT6L58AT

### VHF~UHF Band Low Noise Amplifier Applications

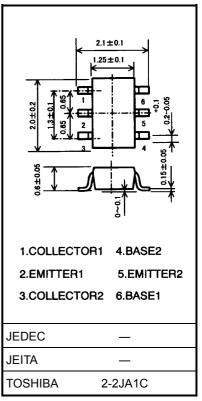
• Two devices are built in to the super-thin and ultra super mini (6 pins) package: TU6

#### **Mounted Devices**

	Q1: SSM (TESM)	Q2: SSM (TESM)
Three-pins (SSM/TESM) mold products are corresponded.	MT3S06S	MT3S03AS
	(MT3S06T)	(MT3S03AT)

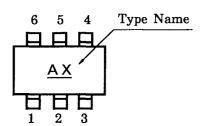
#### Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Q1	Q2	Unit
Collector-base voltage	V <sub>CBO</sub>	10	10	V
Collector-emitter voltage	V <sub>CEO</sub>	5	5	V
Emitter-base voltage	V <sub>EBO</sub>	1.5	2	V
Collector current	۱ <sub>C</sub>	15	40	mA
Base current	Ι <sub>Β</sub>	7	10	mA
Collector power dissipation	P <sub>C</sub>	150		mW
Junction temperature	Tj	125		°C
Storage temperature range	T <sub>stg</sub>	-55~125		°C

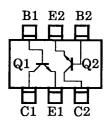


Weight: 0.0045 g (typ.)

#### Marking



Pin Assignment (top view)



Unit: mm

## Electrical Characteristics Q1 (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off current	I <sub>CBO</sub>	$V_{CB} = 5 V, I_{E} = 0$	_	_	0.1	μA
Emitter cut-off current	I <sub>EBO</sub>	$V_{EB} = 1 \text{ V}, \text{ I}_{C} = 0$	_	_	1	μA
DC current gain	h <sub>FE</sub>	$V_{CE} = 1 \text{ V}, I_{C} = 5 \text{ mA}$	70	_	140	
Transition frequency	f <sub>T</sub>	$V_{CE} = 3 \text{ V}, \text{ I}_{C} = 5 \text{ mA}$	7	10	—	GHz
Insertion gain	S <sub>21e</sub>   <sup>2</sup> (1)	$V_{CE} = 1 \text{ V}, \text{ I}_{C} = 5 \text{ mA}, \text{ f} = 2 \text{ GHz}$	_	7.5	—	dB
	S <sub>21e</sub>   <sup>2</sup> (2)	$V_{CE} = 3 \text{ V}, \text{ I}_{C} = 7 \text{ mA}, \text{ f} = 2 \text{ GHz}$	4.5	8	—	
Noise figure	NF (1)	$V_{CE} = 1 \text{ V}, \text{ I}_{C} = 3 \text{ mA}, \text{ f} = 2 \text{ GHz}$	_	1.7	3	dB
	NF (2)	$V_{CE} = 3 \text{ V}, I_{C} = 3 \text{ mA}, f = 2 \text{ GHz}$	_	1.6	3	
Reverse transfer capacitance	C <sub>re</sub>	$V_{CB} = 1 \text{ V}, \text{ I}_{E} = 0, \text{ f} = 1 \text{ MHz} \qquad (\text{Note})$	_	0.35	0.75	pF

Note: Cre is measured by 3 terminal method with capacitance bridge.

### **Electrical Characteristics Q2 (Ta = 25°C)**

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Collector cut-off current	I <sub>CBO</sub>	$V_{CB} = 5 V, I_E = 0$	_		0.1	μA	
Emitter cut-off current	I <sub>EBO</sub>	$V_{EB} = 1 \text{ V}, I_{C} = 0$	_		1	μA	
DC current gain	h <sub>FE</sub>	$V_{CE} = 1 \text{ V}, I_{C} = 5 \text{ mA}$	80	_	160		
Transition frequency	f <sub>T</sub> (1)	$V_{CE} = 1 \text{ V}, I_{C} = 5 \text{ mA}$	5	7	—	GHz	
	f <sub>T</sub> (2)	$V_{CE} = 3 \text{ V}, I_{C} = 10 \text{ mA}$	7	10	_		
Insertion gain	S <sub>21e</sub>   <sup>2</sup> (1)	$V_{CE} = 1 \text{ V}, I_C = 5 \text{ mA}, f = 2 \text{ GHz}$	_	5	_	dB	
	S <sub>21e</sub>   <sup>2</sup> (2)	$V_{CE} = 3 \text{ V}, I_{C} = 20 \text{ mA}, f = 2 \text{ GHz}$	3	6.5	_		
Noise figure	NF (1)	$V_{CE} = 1 \text{ V}, I_C = 5 \text{ mA}, f = 2 \text{ GHz}$	_	1.7	3	dB	
	NF (2)	$V_{CE} = 3 \text{ V}, I_{C} = 7 \text{ mA}, f = 2 \text{ GHz}$		1.4	2.2		
Reverse transfer capacitance	C <sub>re</sub>	$V_{CB} = 1 \text{ V}, \text{ I}_{E} = 0, \text{ f} = 1 \text{ MHz} \qquad (\text{Note})$	_	0.8	1.15	pF	

Note: Cre is measured by 3 terminal method with capacitance bridge.

## **Handling Precaution**

When handling individual devices (which are not yet mounted on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

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